- TG MIN .: 150 °C - TD MIN .: 310 °C EXCEPT ON CN21 BORDERS, AS INDICATED IN GERBER 2. HOLE CHARACTERISTICS: - PLATED HOLE TOLERANCE: +/- 0.1 mm - NON PLATED HOLE TOLERANCE: +/- 0.1 mm - DISPLACEMENT: 0.1 mm MAX. - Cu THICKNESS ON HOLE: 20 um + SnPb MIN. 3. FINISHING: - HOT AIR SOLDER LEVELING (HASL) - SnPb DRIVERS\_LVDS - 1\_01 NOV/2016 IMT - NSEE MAUÁ FDI FD2 **II** 0 • 🔳 **III G** SCN15 • 66,04

REVISIONS DESCRIPTION:

1 00 - Initial revision - jul-22-2016 1\_01 - R1 pull down + R4 pull up + SpW groups silks + test points - nov/2016

TOP / BOTTOM: GND PLANE + SIGNALS

## **GENERAL NOTES:**

AUTHOR: CCB

CODE NUMBER: REVISION: 1\_01 LAYER STACKUP:

## 1. LAMINATE SPECIFICATIONS:

- TOTAL THICKNESS: 1.6 mm +/- 0.2 mm - LAYER NUMBERS: 2

BOARD TITLE: DRIVERS\_LVDS

- Cu THICKNESS (FINISHED): 1 oz / 1 oz
- RAW MATERIAL: FR-4

- 4. SILKSCREEN MASK:
  - WHITE (THERMAL CURE EPOXY)
  - 5. SOLDER MASK:
  - BOTH SIDES
  - GREEN EPOXY THERMAL CURE OR PHOTO IMAGEABLE - JONIC CONTAMINATION AFTER SOLDERING: 14 ug NaCI / in2 MAX.
  - COVER VIAS WITH SOLDER MASK ON BOTH SIDES
  - 6. SPECIFIED STANDARDS:
  - IPC-6011 CLASS 2 / IPC-6012 CLASS 2 / IPC-A-600 CLASS 2
  - 7. ADDITIONAL NOTES:
  - DIMENSIONAL TOLERANCE: +/- 0.2 mm
  - ELECTRICAL TESTS ARE MANDATORY
  - GERBER MODIFICATIONS ARE ONLY ALLOWED WITH EXPLICIT AUTHOR / RESPONSIBLE AUTHORIZATION

